

AMPHENOL TCS

TB-2003

HDM BACKPLANE POWER MODULE INSERTION TOOL
PART NO. 694-0586-000

REVISION "D"

SPECIFICATION REVISION STATUS

<u>Revision</u>	<u>SCR No.</u>	<u>Description</u>	<u>Initial</u>	<u>Date</u>
"B"	26373	Revised in its Entirety	D. Smith	12-18-98
"C"	28976	Revised Paragraph 2.7	R. Roody	9-16-99
"D"	S0079	Replaced template format	M.Lee	02-01-06

Amphenol TCS

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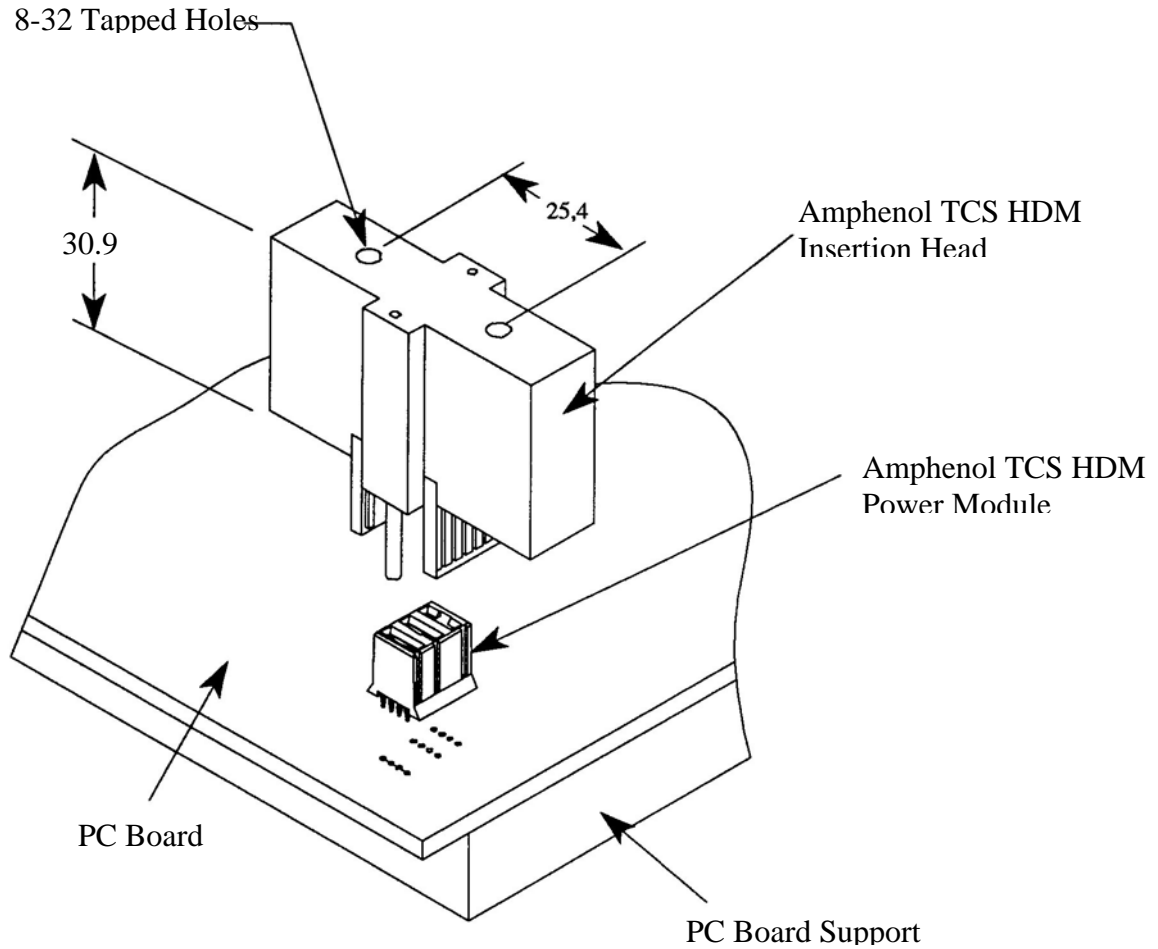


Figure 1

1.0 SCOPE

- 1.1 This technical bulletin covers Amphenol TCS HDM Manual Insertion Tool, Part No. 694-0586-000. This tool is used to press the HDM power module, Part No. 437-5021-000, into printed circuit boards.

2.0 PROCEDURE

2.1 The tool is intended to be used with a manual/hydraulic assisted press. The tool comes with two 8-32 tapped holes to be used to adapt this head to your current press.

2.2 Press Requirements

2.2.1 The press used with this tool must be capable of applying 270 kilograms (maximum) per module. The ability to lock the head and the printed circuit board in location is recommended before applying pressure.

2.3 Insertion

2.3.1 Preload the module into the printed circuit board until the contact retention area starts to enter the board. Note that the pin field pattern can only be loaded one way into the board.

2.3.2 Place the preloaded board onto the printed circuit board support.

NOTE: On thin boards where the contacts will protrude after pressing, ensure that the support has the same drill pattern as the board and that the board is aligned.

2.3.3 Lower the loading head slowly, verifying that the head and module align. The head and module are keyed and can only mate one way.

2.3.4 Apply pressure until the module is fully seated.

2.3.5 Retract the loading head.

2.3.6 Repeat Paragraphs 2.3.1 through 2.3.5 until all modules are seated.

2.4 Seated Module Requirements

2.4.1 The seated module should meet the requirements outlined in Figure 2.

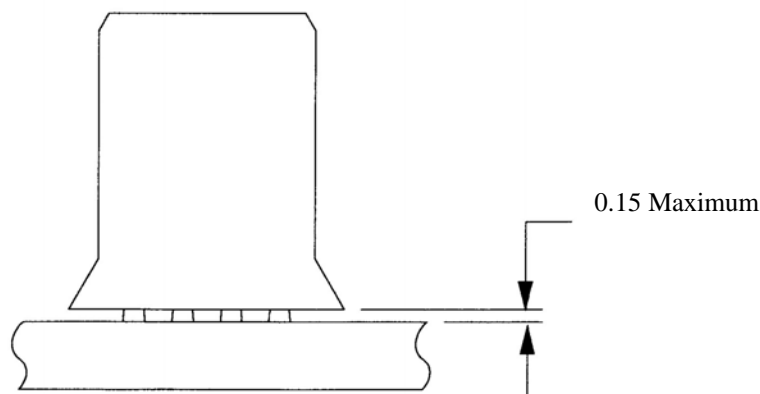


Figure 2

2.5 Quality

2.5.1 This tooling has been inspected before shipment. It is recommended that you unpack and inspect the tool immediately to ensure that it has not been damaged during shipping.

2.6 Related HDM Tooling

Tool	Part No.	Bulletin
Backplane Contact Knock-Out Tool	600-1692-000	TB-2007
Backplane Single Contact Insertion Tool	600-1718-000	TB-2011
Backplane Power Module Removal Tool	600-1693-000	TB-2005
Backplane Power Contact Removal Tool	600-1694-000	TB-2006
Backplane Insulator Removal Tool, 144 Positions	600-1697-000	TB-2004
Backplane Insulator Removal Tool, 72 Positions	600-1698-000	TB-2004
Backplane Polarizing and Guide Pin Assembly Press	602-0549-000	TB-2002
Backplane Signal Module Loading Head, 144 Positions	694-0581-000	TB-2001
Backplane Signal Module Loading Head, 72 Positions	694-0655-000	TB-2001
Backplane Power Module Loading Head	694-0586-000	TB-2003
Daughtercard Module Polarizing Key Removal Tool	602-0525-000	TB-2008
Daughtercard Module Polarizing Key Insertion Tool	602-0555-000	TB-2009
Daughtercard Module Removal Tool	600-1701-000	TB-2010

2.7 Customer Service and Technical Support for Amphenol TCS connectors is available from:

Amphenol TCS

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